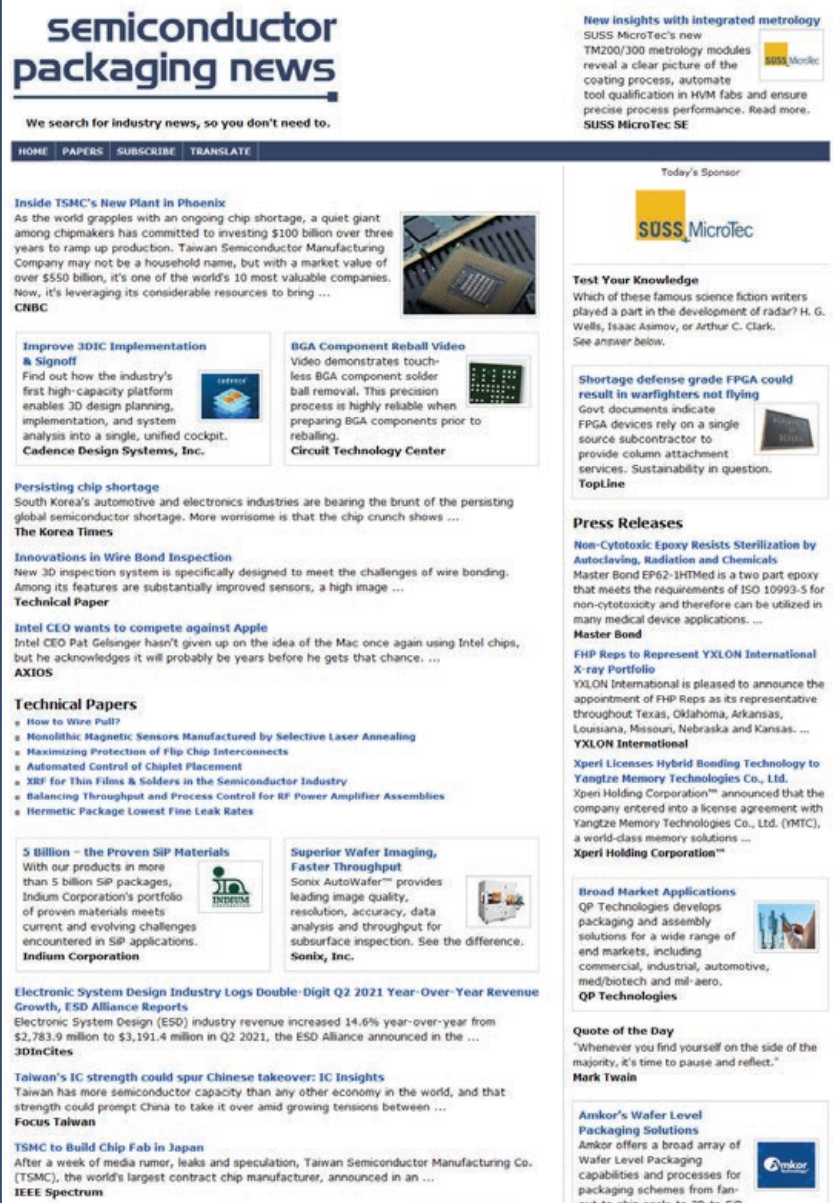


semiconductor packaging news

We search for industry news, so you don't need to.

2024 Media Guide



The screenshot displays the website's layout, which includes a top navigation bar with links for HOME, PAPERS, SUBSCRIBE, and TRANSLATE. The main content area is organized into several columns. The left column features a large article titled 'Inside TSMC's New Plant in Phoenix' with a sub-headline about a \$100 billion investment. Below this are sections for 'Improve 3DIC Implementation & Signoff' and 'Persisting chip shortage'. The middle column contains a 'Technical Papers' section with a list of articles, a '5 Billion - the Proven SIP Materials' section, and a 'Superior Wafer Imaging, Faster Throughput' section. The right column includes a 'New Insights with integrated metrology' section, a 'Test Your Knowledge' quiz, a 'Shortage defense grade FPGA could result in warfighters not flying' article, and a 'Press Releases' section. The bottom of the page features a 'Quote of the Day' and a 'Focus Taiwan' section.

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HOME PAPERS SUBSCRIBE TRANSLATE

Inside TSMC's New Plant in Phoenix
As the world grapples with an ongoing chip shortage, a quiet giant among chipmakers has committed to investing \$100 billion over three years to ramp up production. Taiwan Semiconductor Manufacturing Company may not be a household name, but with a market value of over \$550 billion, it's one of the world's 10 most valuable companies. Now, it's leveraging its considerable resources to bring ...
CNBC

Improve 3DIC Implementation & Signoff
Find out how the industry's first high-capacity platform enables 3D design planning, implementation, and system analysis into a single, unified cockpit.
Cadence Design Systems, Inc.

BGA Component Reball Video
Video demonstrates touchless BGA component solder ball removal. This precision process is highly reliable when preparing BGA components prior to reballing.
Circuit Technology Center

Persisting chip shortage
South Korea's automotive and electronics industries are bearing the brunt of the persisting global semiconductor shortage. More worrisome is that the chip crunch shows ...
The Korea Times

Innovations in Wire Bond Inspection
New 3D inspection system is specifically designed to meet the challenges of wire bonding. Among its features are substantially improved sensors, a high image ...
Technical Paper

Intel CEO wants to compete against Apple
Intel CEO Pat Gelsinger hasn't given up on the idea of the Mac once again using Intel chips, but he acknowledges it will probably be years before he gets that chance. ...
AXIOS

Technical Papers

- How to Wire Pull?
- Monolithic Magnetic Sensors Manufactured by Selective Laser Annealing
- Maximizing Protection of Flip-Chip Interconnects
- Automated Control of Chiplet Placement
- XXF for Thin Films & Solders in the Semiconductor Industry
- Balancing Throughput and Process Control for RF Power Amplifier Assemblies
- Hermetic Package Lowest Fine Leak Rates

5 Billion - the Proven SIP Materials
With our products in more than 5 billion SIP packages, Indium Corporation's portfolio of proven materials meets current and evolving challenges encountered in SIP applications.
Indium Corporation

Superior Wafer Imaging, Faster Throughput
Sonix AutoWafer™ provides leading image quality, resolution, accuracy, data analysis and throughput for sub-surface inspection. See the difference.
Sonix, Inc.

Electronic System Design Industry Logs Double-Digit Q2 2021 Year-Over-Year Revenue Growth, ESD Alliance Reports
Electronic System Design (ESD) industry revenue increased 14.6% year-over-year from \$2,783.9 million to \$3,191.4 million in Q2 2021, the ESD Alliance announced in the ...
3DInCites

Taiwan's IC strength could spur Chinese takeover: IC Insights
Taiwan has more semiconductor capacity than any other economy in the world, and that strength could prompt China to take it over amid growing tensions between ...
Focus Taiwan

TSMC to Build Chip Fab in Japan
After a week of media rumor, leaks and speculation, Taiwan Semiconductor Manufacturing Co. (TSMC), the world's largest contract chip manufacturer, announced in an ...
IEEE Spectrum

New Insights with integrated metrology
SUSS MicroTec's new TM200/300 metrology modules reveal a clear picture of the coating process, automate tool qualification in HyM fabs and ensure precise process performance. Read more.
SUSS MicroTec SE

Today's Sponsor
SUSS MicroTec

Test Your Knowledge
Which of these famous science fiction writers played a part in the development of radar? H. G. Wells, Isaac Asimov, or Arthur C. Clark.
See answer below.

Shortage defense grade FPGA could result in warfighters not flying
Govt documents indicate FPGA devices rely on a single source subcontractor to provide column attachment services. Sustainability in question.
TopLine

Press Releases

Non-Cytotoxic Epoxy Resists Sterilization by Autoclaving, Radiation and Chemicals
Master Bond EP62-1H/ME6 is a two part epoxy that meets the requirements of ISO 10993-5 for non-cytotoxicity and therefore can be utilized in many medical device applications. ...
Master Bond

FHP Reps to Represent YXLON International X-ray Portfolio
YXLON International is pleased to announce the appointment of FHP Reps as its representative throughout Texas, Oklahoma, Arkansas, Louisiana, Missouri, Nebraska and Kansas. ...
YXLON International

Xperi Licenses Hybrid Bonding Technology to Yangtze Memory Technologies Co., Ltd.
Xperi Holding Corporation™ announced that the company entered into a license agreement with Yangtze Memory Technologies Co., Ltd. (YMTC), a world-class memory solutions ...
Xperi Holding Corporation™

Broad Market Applications
QP Technologies develops packaging and assembly solutions for a wide range of end markets, including commercial, industrial, automotive, med/biotech and mil-aero.
QP Technologies

Quote of the Day
"Whenever you find yourself on the side of the majority, it's time to pause and reflect."
Mark Twain

Amkor's Wafer Level Packaging Solutions
Amkor offers a broad array of Wafer Level Packaging capabilities and processes for packaging schemes from fan-out to chip scale to 3D to SiP.
Amkor

- 30,000+ daily e-mail subscribers
- 125,000 unique visitors past 12 months
- Readership from 130 countries
- #1 newsletter and website for industry professionals

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Why Advertise With Semiconductor Packaging News?

Digital media continues to expand as industry professionals seek daily updates on news and events shaping the semiconductor packaging and micro-electronics market. An advertising campaign in Semiconductor Packaging News provides excellent visibility with high-frequency advertising designed to meet every budget. We reach 125,000 industry professionals who are eager to learn more about your products and services.

A digital advertising campaign features:

- Lead generation and advertising in the daily newsletter & website
- Banner ads for branding (160 x 300 pixels vertical)
- Text ads intrigue readers to click to your web pages to learn more
- Technical papers provide lead generation for your sales channel
- Corporate news releases published daily at no cost
- Calendar to post your shows, webcasts and important events
- Custom e-mail broadcast to SPN subscribers dedicated to your company

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Analytical Data

Recent analytical data collected from an independent company confirms our readership continues to expand. Semiconductor Packaging News e-mail newsletter is broadcast to 30,000 subscribers every business day.



During the past 12-months Semiconductor Packaging News has reached over 125,000 unique visitors from 130 countries. The e-mail newsletter subscriber base is always up-to-date and is managed by an independent e-mail company.

Top 10 markets by geographic readership:

- | | |
|-----------------|------------------|
| ▪ North America | ▪ China |
| ▪ Japan | ▪ Singapore |
| ▪ South Korea | ▪ Netherlands |
| ▪ Taiwan | ▪ United Kingdom |
| ▪ Germany | ▪ France |

Demographics by region of the world:
45% Americas, 33% Asia Pacific, and 22% Europe

Industry organizations such as SEMI, IMAPS, MEPTEC, IEEE partner with Semiconductor Packaging News to reach their members and drive visitors to their events and trade shows.

Comments from several Semiconductor Packaging News advertisers:

"SPN provides a great opportunity to reach a range of prospects on a daily basis for a very competitive price. We can advertise for an entire year for the cost of a small booth at a local show."
J.B.

"The White Paper program in SPN has delivered hundreds of prospects from around the world. This is a great way to reach new customers."
R.H.

"We are very pleased with the exposure and support from our ad campaign in SPN."
D.P.

"Semiconductor Packaging allows us to reach our markets around the globe. We book new orders from readers of SPN."
J.F.

"In this period of decline in print publications, our users are turning to the web as the source of information. We have benefited from our aggressive use of SPN as an advertising vehicle."
R.B.

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Semiconductor Packaging News Readers

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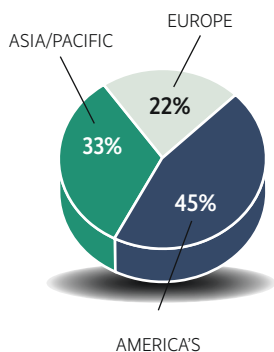
Over 30,000 daily subscribers find Semiconductor Packaging News to be their go-to source for news and information in the semiconductor and micro-electronics assembly market. Semiconductor Packaging News subscribers and website visitors are the industry professionals you want to reach; they are your prospects and your customers.

Rather than waiting for an issue of a trade publication every month or two, our daily e-mail broadcast reaches professionals that have a need to know – and who bear the responsibility for looking ahead to keep their companies on top! They keep themselves up to speed by reading Semiconductor Packaging News daily. Over 500,000 articles have been clicked and read by Semiconductor Packaging News readers.

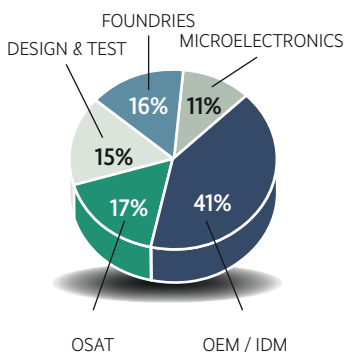


Based on a readership survey we are proud to share data and commentary from industry professionals who took part in our survey.

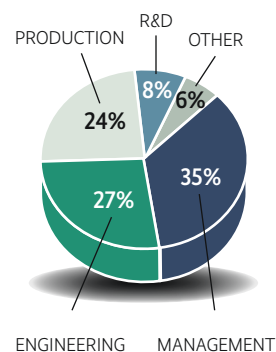
Readership
Breakdown



Company Type



Job Description



Comments from several Semiconductor Packaging News subscribers:

"Semiconductor Packaging News is the only daily newsletter focused on the packaging side of the industry."

"SPN is the best daily newsletter, I look forward to reading each day."

"This is the best daily newsletter for insight on the micro-electronics and semiconductor industries."

"I read SPN regularly and find the mix of information to be quite interesting."

"As an Asia Pacific reader, I find your newsletter useful to gain the global perspective on the growing 3D packaging."

"All the important news in one place, great way to start my morning."

"Nice Job. Really stands out. Very newswy with lots of good stuff."

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Advertising Opportunities

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Semiconductor Packaging News advertising delivers results. We deliver your message to a targeted readership with the highest frequency. Advertising campaigns in Semiconductor Packaging News provide more visibility compared to other weekly newsletters and print media. The more often your ads run, the more response you will receive.

Banner Ads

Banner Ads are ideal for branding with corporate colors and a company logo. Large banner ads (160 x 300 pixels) provide significant space to deliver your messages for maximum exposure.

Text Ads

A well written text ad will intrigue the reader to click the ad to learn more about your product or service. The goal of a text ad is to deliver readers directly to your website. We encourage advertisers to run multiple text ads in their ad campaign at no extra cost.

Top Sponsor Position

Gold and silver-plus sponsors will have a "text ad" at the top of the newsletter and website once each month. Today's Sponsor includes the company's logo on the same day as the text on the top right column. Gold and silver-plus advertisers also receive premium positions each month.

Technical Papers generate leads each month

Semiconductor Packaging publishes relevant technical papers at no cost allowing readers to download them with a simple registration. We gather the name, company and e-mail addresses and provide to our advertisers at no additional cost.

Geo-Targeting

The geo-targeting feature allows your banner ads and text ads to be delivered to readers in a specific continent or country. A great method to reach a select group of readers to introduce a new product to a specific market, publicize a webinar or promote an award. Ask for more details.

Custom E-mail Broadcast

A custom e-mail broadcast to our subscribers can showcase new products, promote a webinar, conference or award. The custom e-mail broadcast will be focused exclusively on your company. Ask us for more details.

Monthly Media Reports

Semiconductor Packaging News provides a monthly media report capturing data from your campaign including banner ad and text ad views and clicks. We also gather the names of readers who download the published technical papers to share with your sales channel.

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Amkor Technology

To view monthly reports for advertisements in the Semiconductor Packaging News email newsletter

Monthly Reports

Sep 2023, Sep 2023, Aug 2023, Aug 2023, Jul 2023, Jul 2023, Jun 2023, Jun 2023, May 2023, May 2023, Apr 2023, Apr 2023, Mar 2023, Mar 2023, Feb 2023, Feb 2023, Jan 2023, Jan 2023, Dec 2022, Nov 2022, Oct 2022, Sep 2022, Aug 2022, Jul 2022, Jun 2022, May 2022, Apr 2022, Mar 2022, Feb 2022, Jan 2022, Dec 2021, Nov 2021, Oct 2021, Sep 2021, Aug 2021, Jul 2021, Jun 2021, May 2021, Apr 2021, Mar 2021, Mar 2021, Feb 2021, Jan 2021, Dec 2020, Nov 2020, Oct 2020, Oct 2020, Sep 2020, Sep 2020, Aug 2020, Aug 2020, Jul 2020, Jun 2020, May 2020, Apr 2020, Mar 2020, Mar 2020, Feb 2020, Feb 2020, Jan 2020, Jan 2020, Dec 2019, Nov 2019, Nov 2019, Oct 2019, Oct 2019, Sep 2019, Sep 2019, Aug 2019, Jul 2019, Jun 2019, May 2019, Apr 2019, Mar 2019, Feb 2019, Jan 2019, Dec 2018, Nov 2018, Oct 2018, Sep 2018, Aug 2018, Jul 2018, Jun 2018, May 2018, Apr 2018, Mar 2018, Mar 2018, Feb 2018, Feb 2018, Jan 2018, Jan 2018, Dec 2017, Dec 2017, Nov 2017, Nov 2017, Oct 2017, Sep 2017, Sep 2017, Aug 2017, Aug 2017,

Recent Press Releases

Submit

Date	Title
Nov 9, 2023	Amkor Technology Signs Commitment to Science-Based Targets Initiative (SBTi)
Oct 12, 2023	Amkor's Newest Factory Opens in Vietnam
Aug 29, 2023	Amkor Technology to Ring the Nasdaq Stock Market Closing Bell
Aug 1, 2023	Amkor Technology Reports Financial Results for the Second Quarter 2023
Jun 22, 2023	Amkor Advanced Packaging Enables the Car of the Future
May 4, 2023	Amkor Reports Financial Results for the First Quarter 2023

Recent Technical/White Papers

Submit

Click "List" to see who downloaded your White Paper.

Date	Title	List
Oct 25, 2023	Revising 5G RF Calibration Procedures For RF IC Production Testing	List
Sep 29, 2023	How AIP/AoP Technology Helps Enable 5G And More	List
Aug 31, 2023	3D Sensing Solutions	List
Jul 25, 2023	Production Testing Of Discrete Power Products	List
Jun 21, 2023	Heterogeneous IC Packaging: Optimizing Performance And Cost	List

Did You Know: Text ads will typically deliver 2-3 times as many clicks as a banner ad. Advertisers use banner ads to build the company brand and text ads to intrigue readers to click on their ads and drive readers to pages on their website.

4

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Rate Card

Premium Positions

Text Ad

Vertical Banner Ads

Sponsor Text Ad

Sponsor Logo

Premium Position

Text Ad

Text Ad

The screenshot displays the homepage of 'semiconductor packaging news'. At the top, there's a navigation bar with links for HOME, PAPERS, SUBSCRIBE, and TRANSLATE. The main content area features several articles, including 'Inside TSMC's New Plant in Phoenix', 'Improve BGA Implementation & Signoff', 'Persisting chip shortage', 'Innovations in Wire Bond Inspection', 'Intel CEO wants to compete against Apple', and 'Technical Papers'. On the right side, there's a 'Sponsor Text Ad' for SUSS MicroTec, a 'Sponsor Logo' for SUSS MicroTec, and a 'Text Ad' for QP Technologies. At the bottom, there are three vertical banner ads for YERSUM, SUPPORTING LONG LIFE CYCLE AUTOMOTIVE APPLICATIONS, and Mitsubishi ZEROSHIFT Thermistor.

Silver Campaign

The Silver Campaign includes 8 days per month in the e-mail newsletter. Ads will usually run twice per week in this campaign. This campaign does not include visibility in the website.

3-month campaign \$1,100/month
6-month campaign \$1,050/month
12-month campaign \$950/month

Silver-Plus Campaign

The Silver-Plus Campaign includes 9 days per month in the e-mail newsletter including a premium ad position each month plus your campaign runs on the website 24/7.

3-month campaign \$1,500/month
6-month campaign \$1,450/month
12-month campaign \$1,350/month

Gold Campaign

The Gold Campaign includes 15 days per month in the e-mail newsletter including a top sponsor position with company logo each month plus your campaign runs on the website 24/7.

3-month campaign \$2,000/month
6-month campaign \$1,900/month
12-month campaign \$1,800/month

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About Us

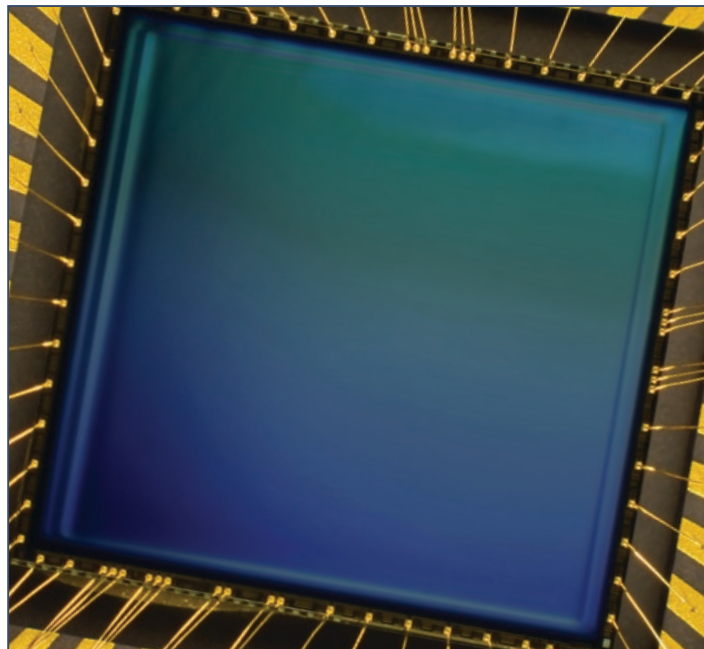
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We believe it's our job to dig through the unending stream of news, articles, features, and discussions to deliver information, covering the world of semiconductor packaging and micro electronics, to our readers. Every night we scour the news from over 100 sources to find the best industry news articles. We package this information into a convenient newsletter that is delivered to our subscribers e-mail every business day.

The Semiconductor Packaging Newsletter and website features links to industry and technology news stories and feature articles about the semiconductor packaging market. We publish the latest corporate and product news announcements industry companies submit to us.

Thousands of technical papers are downloaded every month and we'll publish your technical paper at no cost. You'll also find commentaries, cartoons, an industry event calendar and much more.

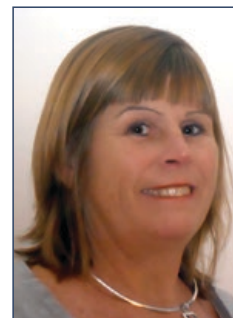
We look forward to working with you on your digital sponsorship campaign.



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